



DT6250-06MR

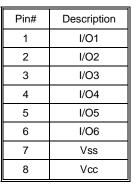
6 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

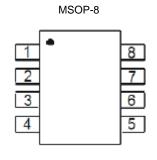
Features

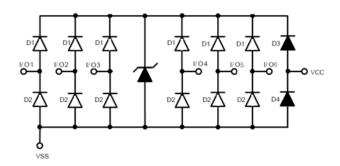
- IEC 61000-4-2 (ESD): Contact ±8kV
- IEC 61000-4-5 (Lightning): 4A (8/20μs)
- 6 Channels of ESD Protection
- Low Channel Input Capacitance of 0.32pF max
- Typically Used at USB 3.0 and High Speed Ports in Any Electronic Product
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: MSOP-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Terminals: NiPdAu over Copper Leadframe (Lead Free Plating).
 Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.027 grams (Approximate)







Pin Description

Top View

Device Schematic

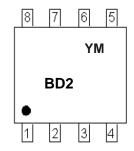
Ordering Information (Note 4)

Product	Compliance	Marking	Reel size(inches)	Tape width(mm)	Quantity per reel
DT6250-06MR-13	Standard	BD2	13	12	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



BD2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	20	13	20	14	20	15	20	16	20	17	20	18
Code	A	4	E	3	())	E		F	=
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	I _{PP}	4	Α	I/O to V _{SS} , 8/20μs
ESD Protection – Contact Discharge	V _{ESD_I/O}	±8	kV	IO to V _{SS} , per IEC 61000-4-2
Operating Temperature	T _{OP}	-40 to +85	°C	_
Storage Temperature	T _{STG}	-55 to +150	°C	_

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	500	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	250	°C/W

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

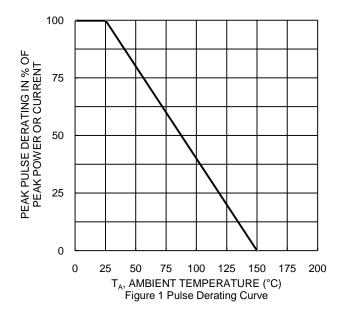
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	V_{RWM}	_	I	5.0	V	V _{CC} to V _{SS}
Reverse Leakage Current (Note 6)	I _{R_VCC}	_	_	2.5	μΑ	V _{CC} = 5V, V _{CC} to V _{SS}
Channel Leakage Current (Note 6)	I_{R_IO}	_	_	1.0	μΑ	V_{CC} = 5V, any I/O to V_{SS}
Reverse Breakdown Voltage	V_{BR}	6	_	_	V	I _{BV} = 1mA, V _{CC} to V _{SS}
Forward Voltage	V _F	_	0.8	1.2	V	I _F = 15mA, V _{SS} to V _{CC}
ESD Clamping Voltage	V _{ESD_I/O}	_	10	_	V	TLP, 10A, tp = 100ns, I/O to V_{SS}
	V_{ESD_VCC}	_	9	_	V	TLP, 10A, tp = 100ns, V_{CC} to V_{SS}
Differential Resistance	R _{DIF_I/O}	_	0.35	_	Ω	TLP, 10A, tp = 100ns, I/O to Vss
Differential Resistance	R _{DIF_VCC}	_	0.25	_	Ω	TLP, 10A, tp = 100ns, V _{CC} to V _{SS}
Channel Input Capacitance	C _{I/O}	_	0.32	_	pF	$V_{I/O} = 2.5V$, $V_{CC} = 5V$, $f = 1MHz$
Delta C _{I/O}	C _{I/OMAX} -C _{I/OMIN}	_	0.05	_	pF	C _{I/OMAX} -C _{I/OMIN}

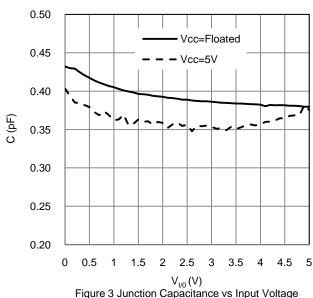
Notes:

^{5.} Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

^{6.} Short duration pulse test used to minimize self-heating effect.







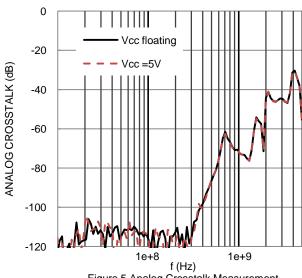
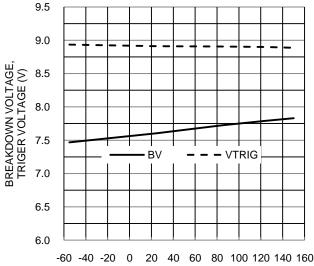
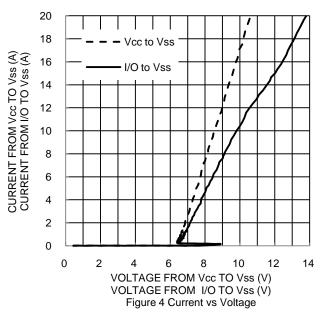


Figure 5 Analog Crosstalk Measurement



T_A, AMBIENT TEMPERATURE (°C) Figure 2 Breakdown Voltage, Trigger Voltage vs Ambient Temperature



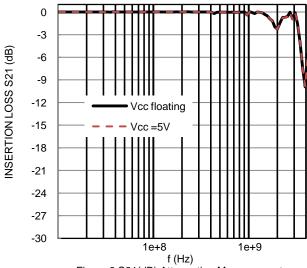
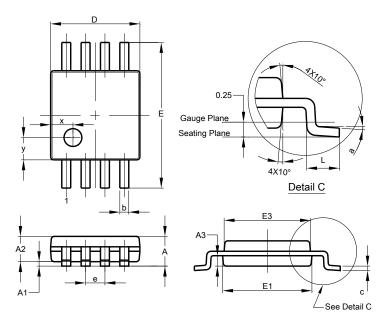


Figure 6 S21(dB) Attenuation Measurement



Package Outline Dimensions

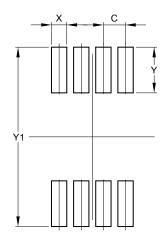
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



MSOP-8						
Dim	Min	Max	Тур			
Α	-	1.10	-			
A1	0.05	0.15	0.10			
A2	0.75	0.95	0.86			
A3	0.29	0.49	0.39			
b	0.22	0.38	0.30			
С	0.08	0.23	0.15			
D	2.90	3.10	3.00			
Е	4.70	5.10	4.90			
E1	2.90	3.10	3.00			
E3	2.85	3.05	2.95			
е	-	-	0.65			
L	0.40	0.80	0.60			
а	0°	8°	4°			
х	-	-	0.750			
У	-	-	0.750			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.650
Х	0.450
Y	1.350
Y1	5.300



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